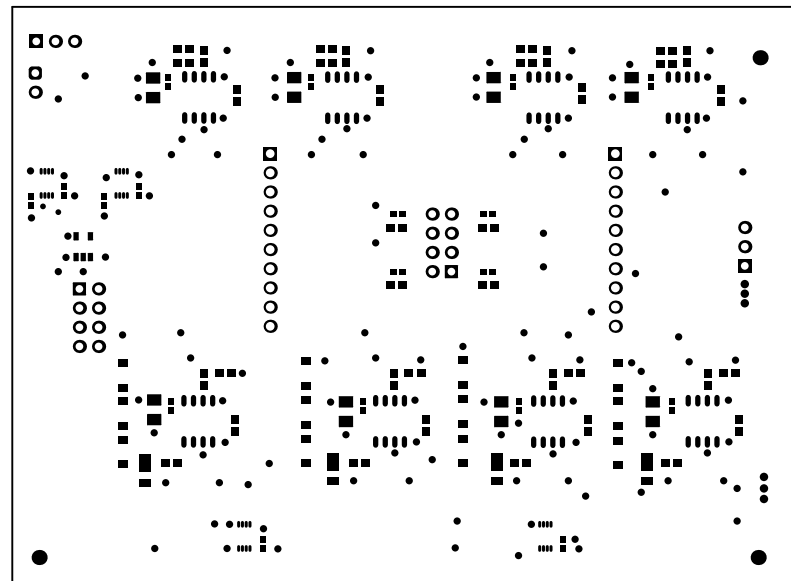
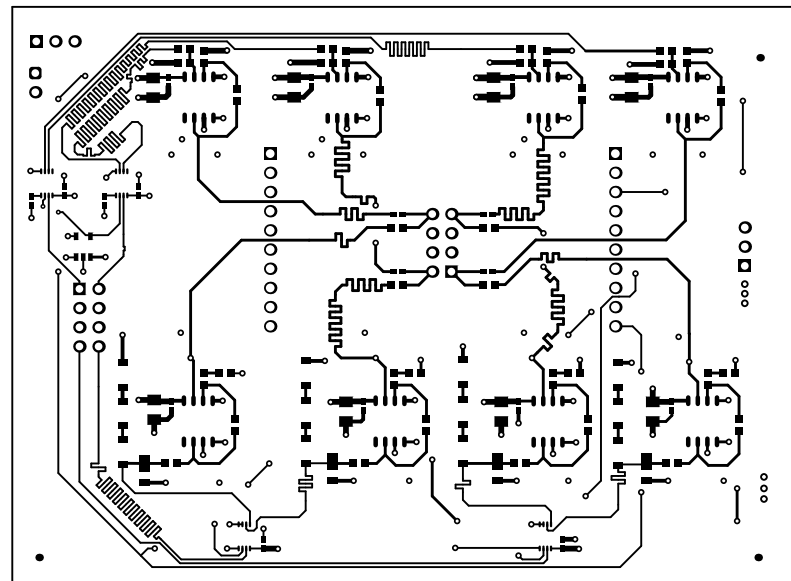


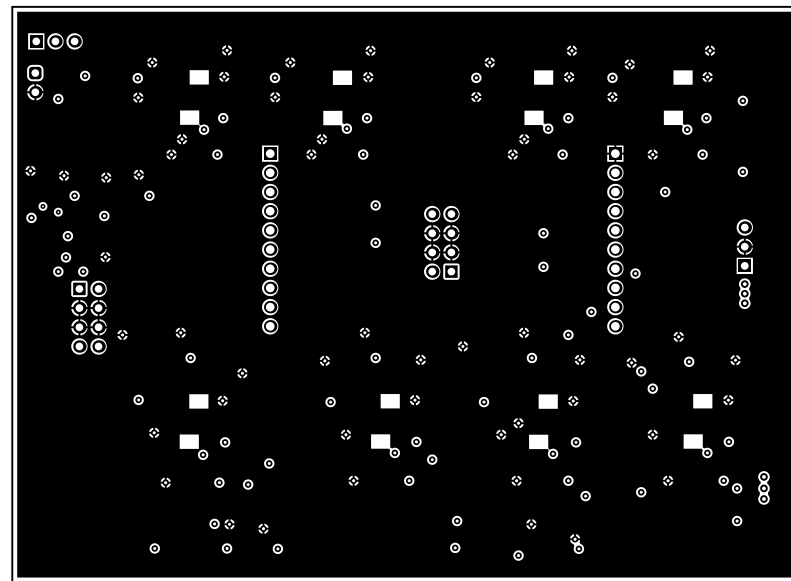
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01486	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01486		
PLOT NAME = Top Overlay	GENERATED : 5/14/2018 1:42:19 PM	TEXAS INSTRUMENTS	



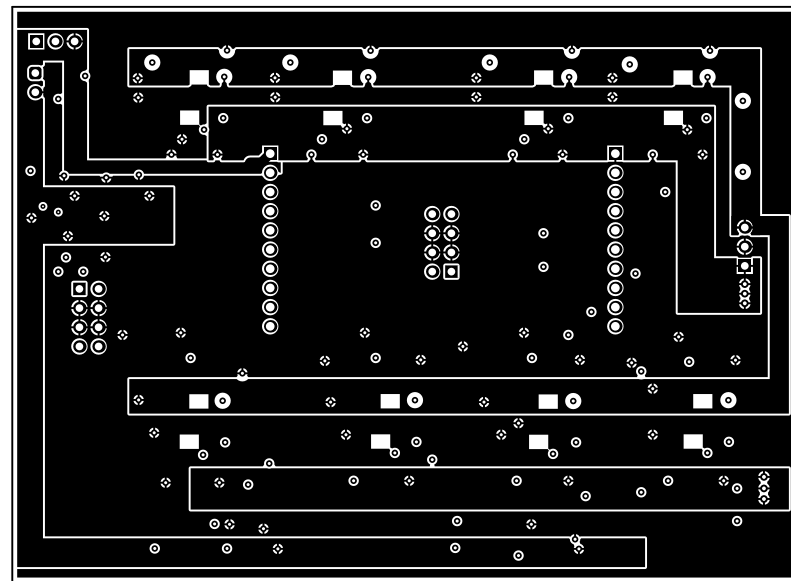
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01486	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01486		
PLOT NAME = Top Solder Mask	GENERATED : 5/14/2018 1:42:20 PM	TEXAS INSTRUMENTS	



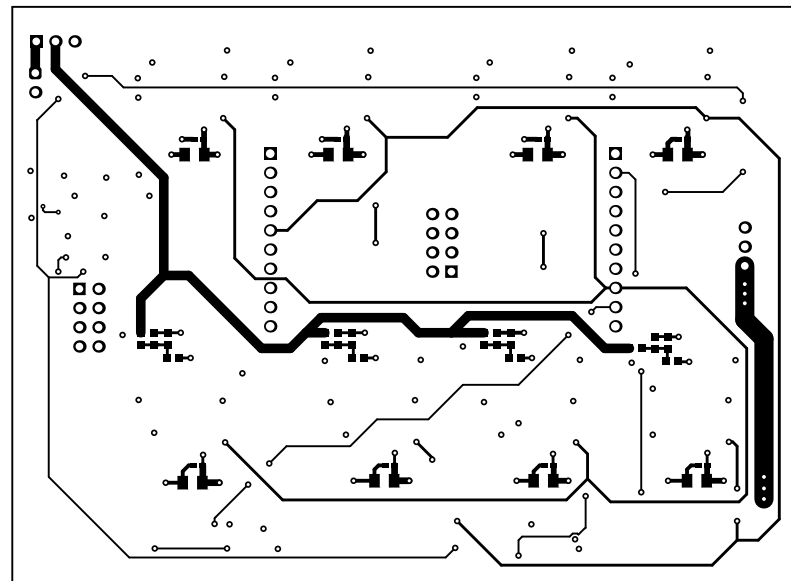
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01486	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-01486		
PLOT NAME = Top Layer	GENERATED : 5/14/2018 1:42:21 PM	TEXAS INSTRUMENTS	



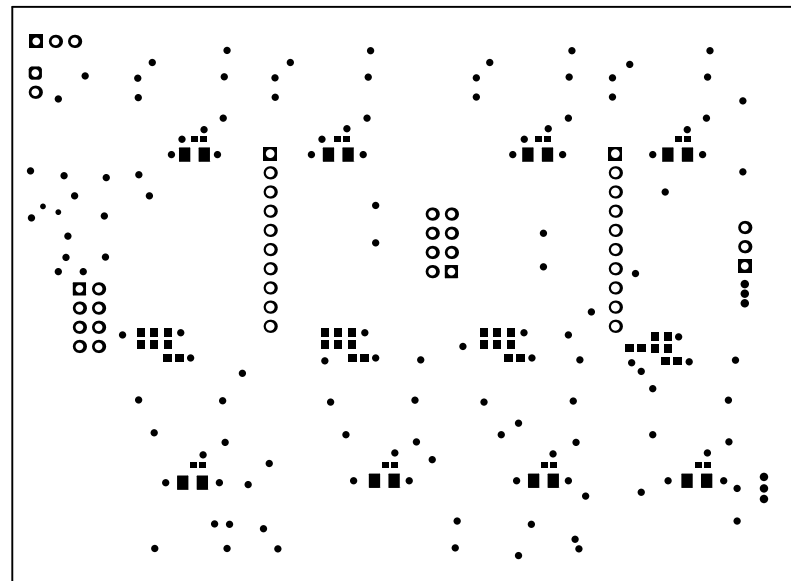
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01486	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01486		
PLOT NAME = Signal Layer 1	GENERATED : 5/14/2018 1:42:22 PM	TEXAS INSTRUMENTS	



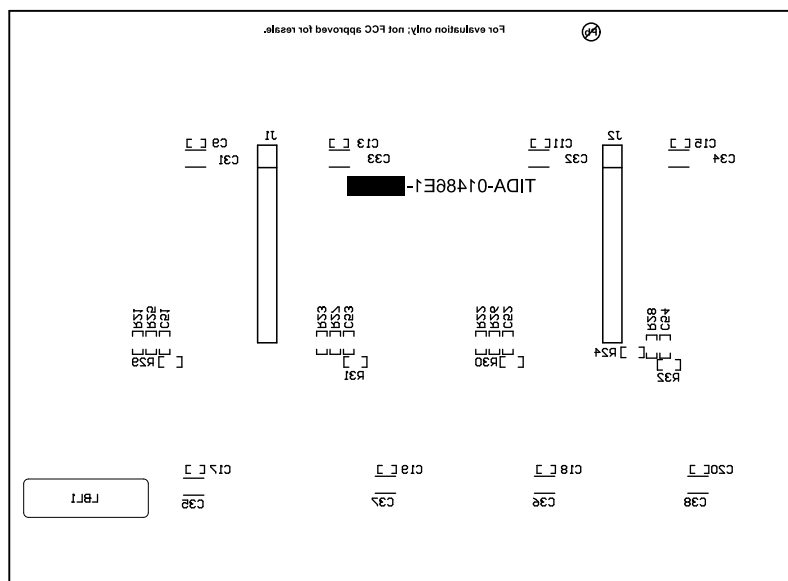
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01486	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01486		
PLOT NAME = Signal Layer 2	GENERATED : 5/14/2018 1:42:23 PM	TEXAS INSTRUMENTS	



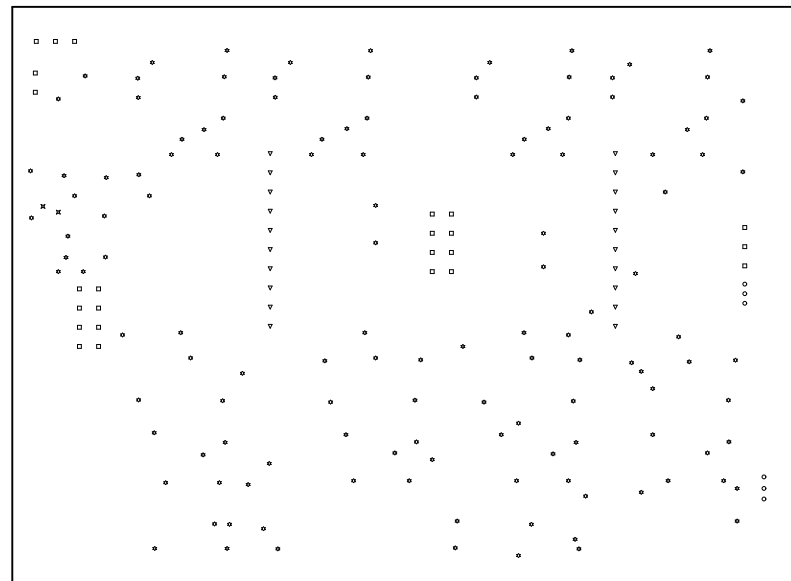
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01486	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-01486		
PLOT NAME = Bottom Layer	GENERATED : 5/14/2018 1:42:25 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01486	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01486		
PLOT NAME = Bottom Solder Mask	GENERATED : 5/14/2018 1:42:26 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01486	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01486		
PLOT NAME = Bottom Overlay	GENERATED : 5/14/2018 1:42:27 PM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
✕	2	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
⊛	129	16.00mil (0.406mm)	PTH	Round	Top Layer - Bottom Layer	
○	6	20.00mil (0.508mm)	PTH	Round	Top Layer - Bottom Layer	
□	24	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
▽	20	45.28mil (1.150mm)	PTH	Round	Top Layer - Bottom Layer	
	181 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01486	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01486		
PLOT NAME = Drill Drawing	GENERATED : 5/14/2018	1:42:28 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01486	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01486		
PLOT NAME = Board Dimensions	GENERATED : 5/14/2018 1:42:29 PM	TEXAS INSTRUMENTS	

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